

100V 15mohm N-channel SGT MOSFET
AKG10N150KM

Description:

This device is designed for automotive applications and manufactured in IATF16949 certified facilities.

Features:

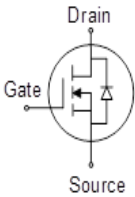
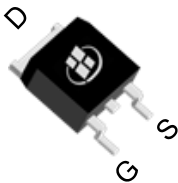
- Low $R_{DS(ON)}$
- RoHS compliant
- Halogen-free

Applications:

- Motor Driving
- DC-DC Converter

Key Performance Parameters:

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(ON), max} @V_{GS} = 10\text{ V}$	15	mΩ
I_D	48	A



Ordering Information:

Ordering Code	Package Type	Marking Code	Form	Packing
AKG10N150KM	TO-252	G10N150KM	Tape Reel	2500 per reel

Maximum Ratings (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Units
V _{DS}	Drain - Source Voltage	100	V
I _D	Drain Current - Continuous (T _C = 25°C) ^(Note 1)	48	A
	Drain Current - Continuous (T _C = 100°C)	31	A
I _{DM}	Drain Current - Pulsed ^(Note 2)	192	A
V _{GS}	Gate-Source Voltage	± 20	V
E _{AS}	Single Pulsed Avalanche Energy ^(Note 3)	56	mJ
P _D	Power Dissipation (T _C = 25°C)	63	W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Value	Units
R _{θJC}	Thermal Resistance, Junction - to - Case, Steady State	2	°C/W
R _{θJA}	Thermal Resistance, Junction - to - Ambient, Steady State ^(Note 4)	55	°C/W

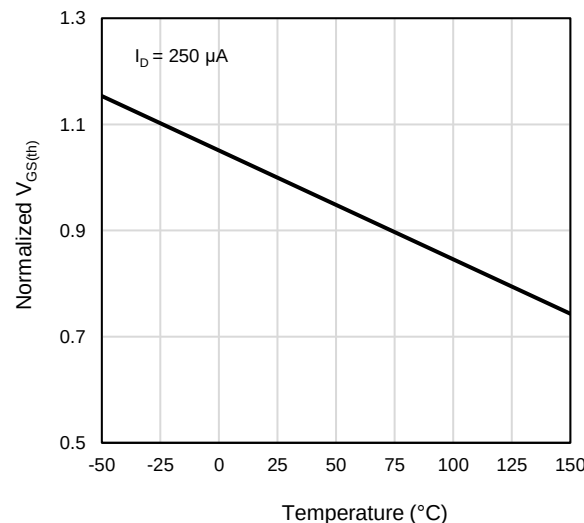
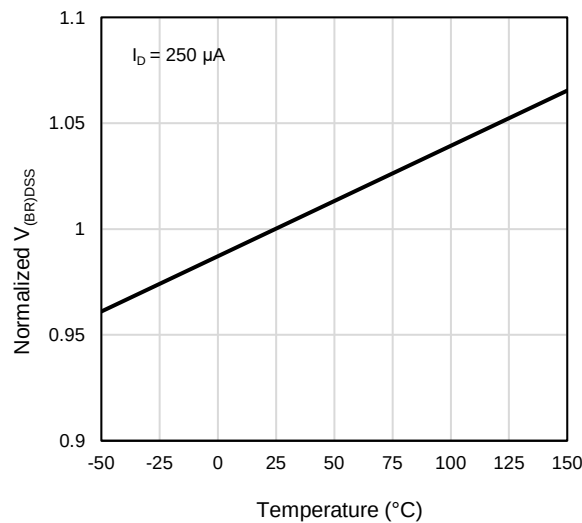
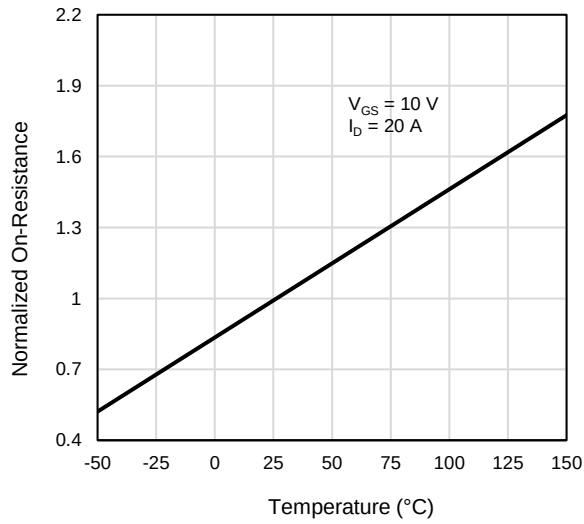
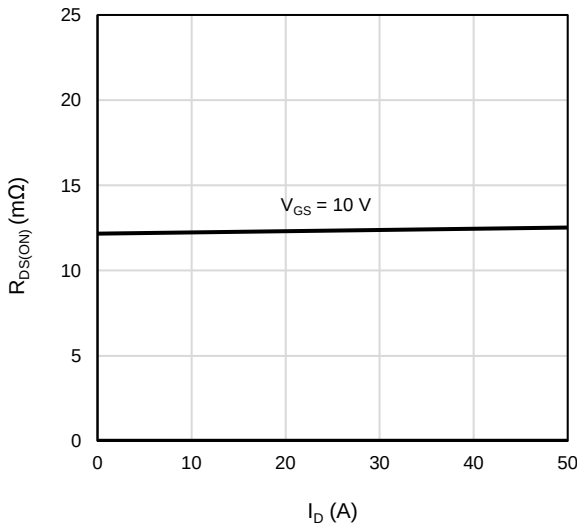
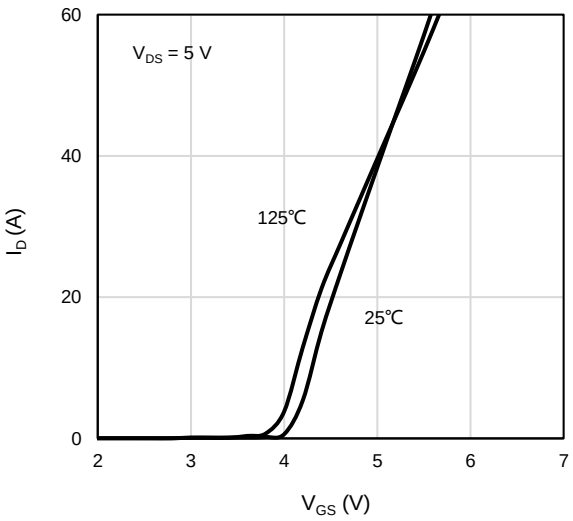
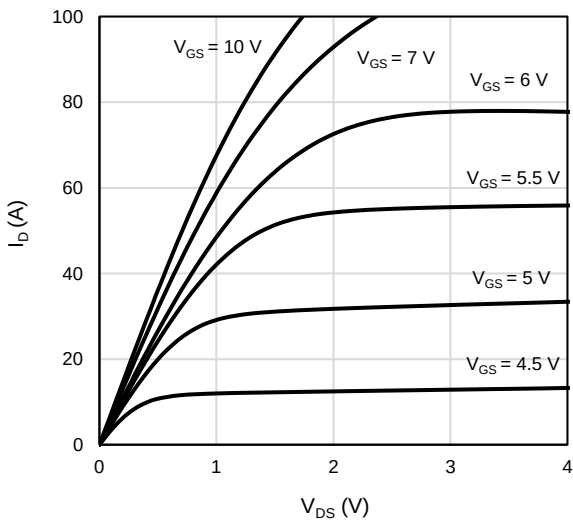
Notes:

- 1. The max drain current rating is silicon limited
- 2. Repetitive Rating: Pulse width limited by maximum junction temperature
- 3. L = 0.5 mH, V_{DD} = 50 V, I_{AS} = 15 A, R_g = 50 Ω, Starting T_J = 25 °C
- 4. Mount on minimum PCB layout

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Static Characteristics						
V _{(BR)DSS}	Drain - Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	100			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100 V, V _{GS} = 0 V,			1	μA
I _{GSS}	Gate Leakage Current	V _{GS} = ± 20 V, V _{DS} = 0 V			±100	nA
V _{GS(th)}	Gate Threshold voltage	V _{DS} = V _{GS} , I _D = 250 μA	2	3	4	V
R _{DS(ON)}	Drain - Source on - state resistance	V _{GS} = 10 V, I _D = 20 A		12.3	15	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		1457		pF
C _{oss}	Output Capacitance			340		pF
C _{rss}	Reverse Transfer Capacitance			21		pF
R _g	Gate Resistance	f = 1 MHz		1.3		Ω
Switching Characteristics						
t _{d(on)}	Turn On Delay Time	V _{DD} = 50 V , R _L = 2.5 Ω, V _{GS} = 10 V, R _G = 6.8 Ω		11		ns
t _r	Rise Time			30		ns
t _{d(off)}	Turn Off Delay Time			22		ns
t _f	Fall Time			10		ns
Q _g	Total Gate Charge	V _{DD} = 50 V , I _D = 20 A, V _{GS} = 10 V		22		nC
Q _{gs}	Gate - Source Charge			6		nC
Q _{gd}	Gate - Drain Charge			8		nC
Drain - Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Body - Diode Forward Current				48	A
I _{SM}	Maximum Pulsed Body - Diode Forward Current				192	A
V _{SD}	Diode Forward Voltage	V _{GS} = 0 V, I _S = 1 A		0.7		V
t _{rr}	Reverse recovery time	V _{DD} = 50 V, I _D = 20 A, di/dt = 100 A/μs		50		ns
Q _{rr}	Reverse recovery charge			70		nC
I _{rrm}	Peak Reverse Recovery Current			2.5		A

Electrical Characteristics Diagrams



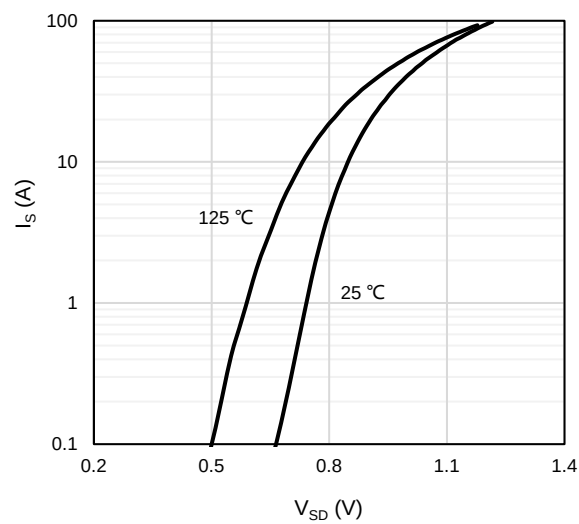


Figure 7: Body-Diode Characteristics

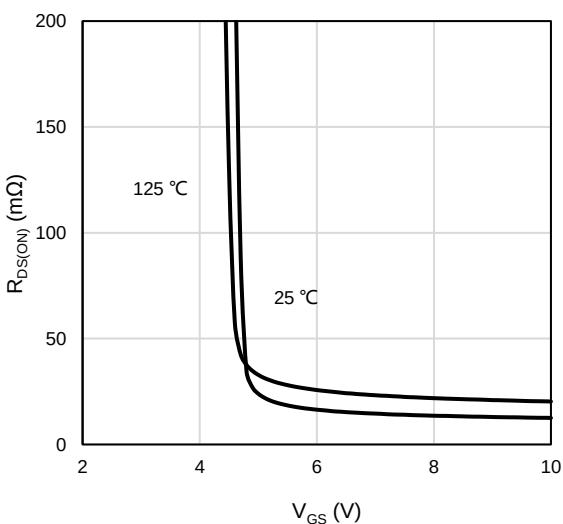


Figure 8: On-Resistance vs. Gate-Source Voltage

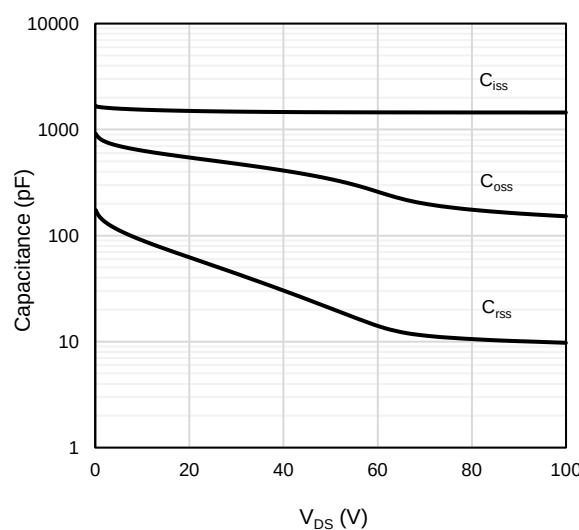


Figure 9: Capacitance Characteristics

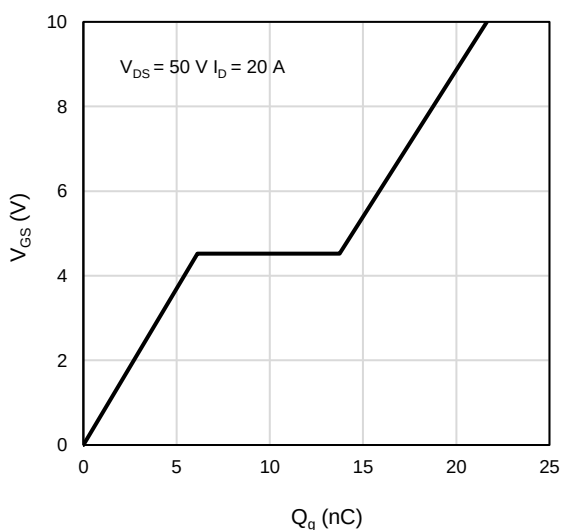


Figure 10: Gate-Charge Characteristics

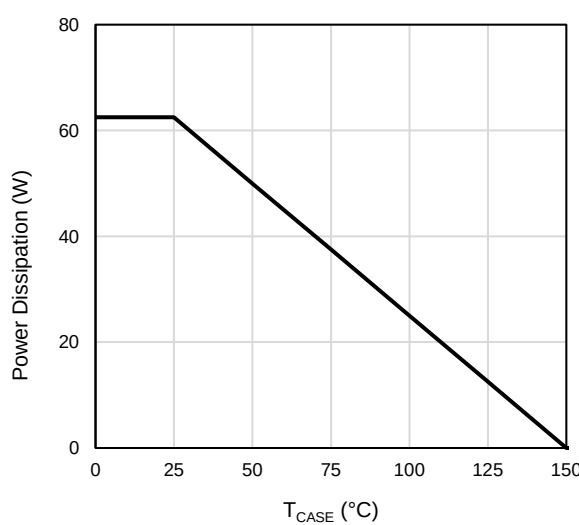


Figure 11: Power De-rating

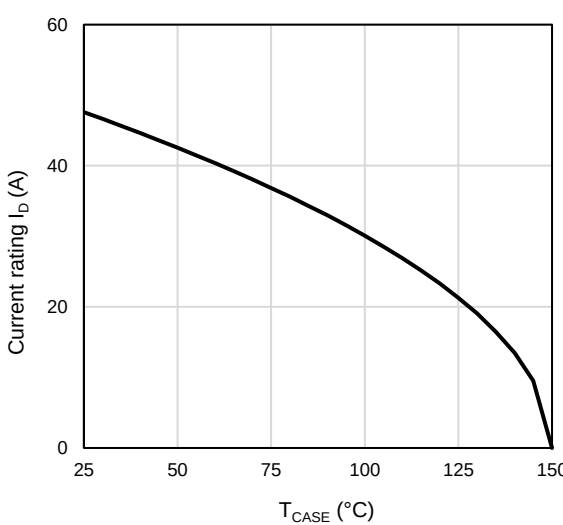


Figure 12: Current De-rating

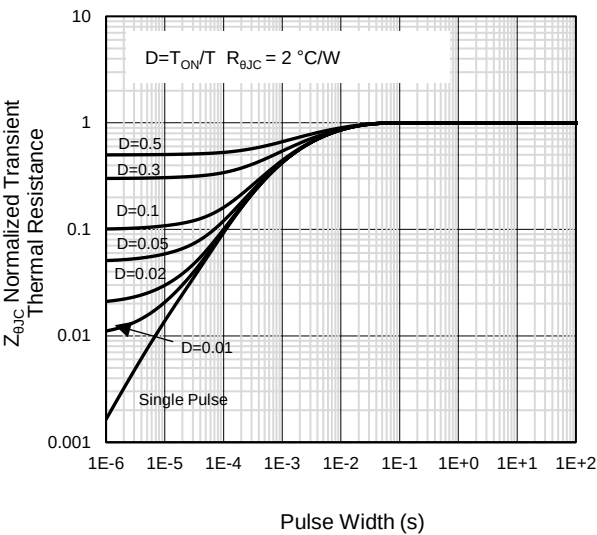


Figure 13: Normalized Maximum Transient Thermal Impedance

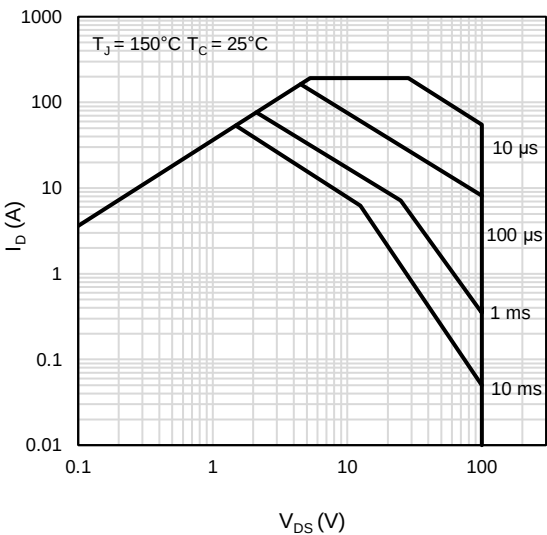
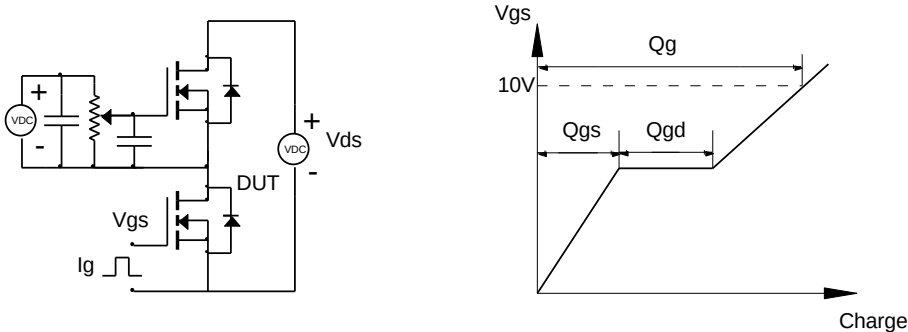


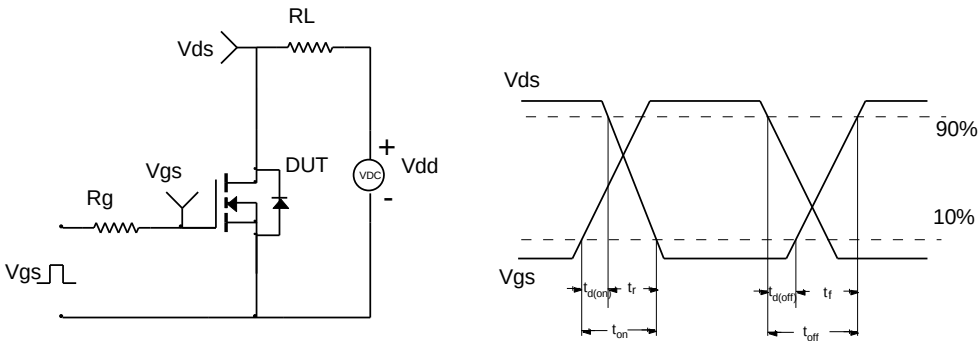
Figure 14: Maximum Forward Biased Safe Operating Area

Test Circuit and Waveform

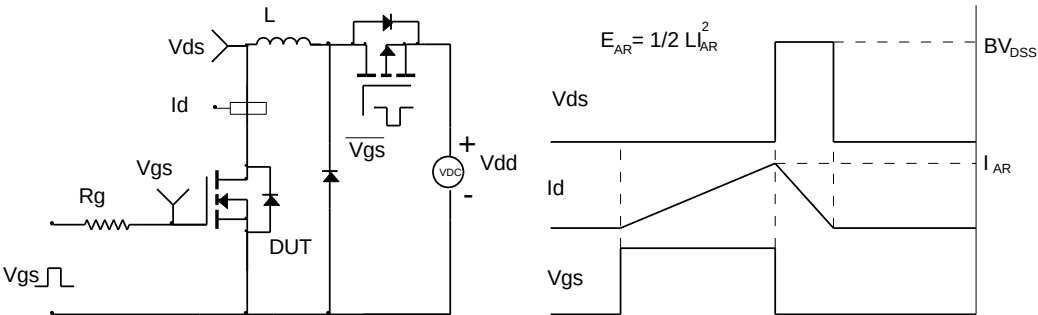
Gate Charge Test Circuit & Waveform



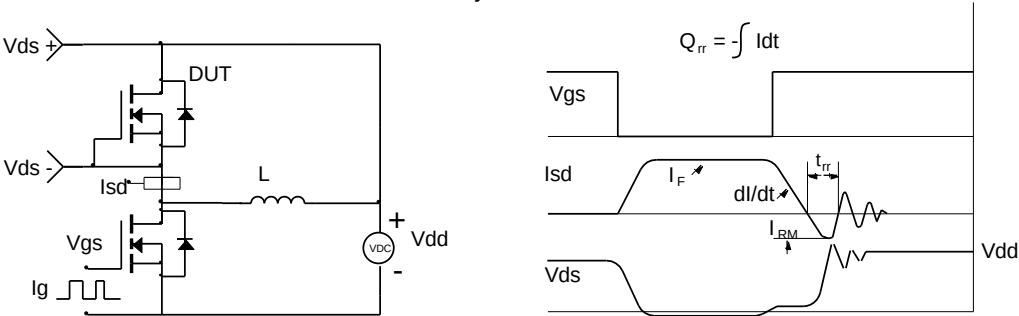
Resistive Switching Test Circuit & Waveforms



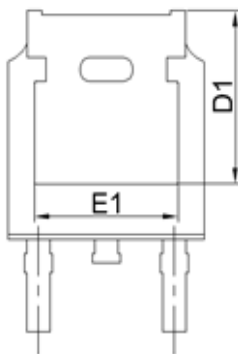
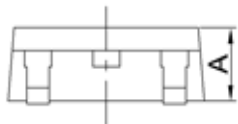
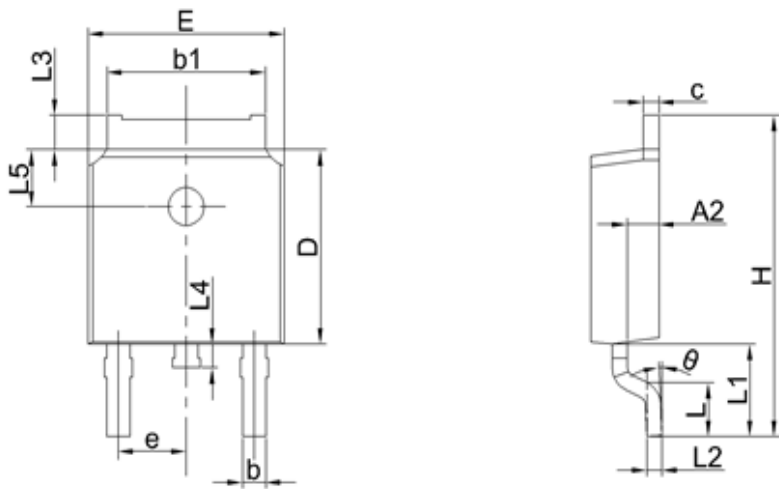
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outlines



SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	0.06	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b1	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30 REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286 BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90 REF		
L2	0.51 BSC		
L3	0.88	1.08	1.28
L4	0.50	0.75	1.00
L5	1.65	1.80	1.95
θ	0°	4°	8°

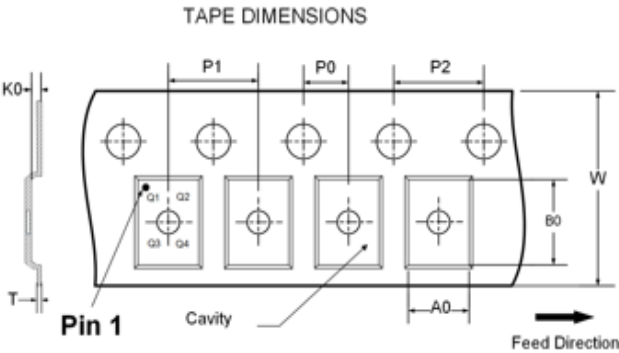
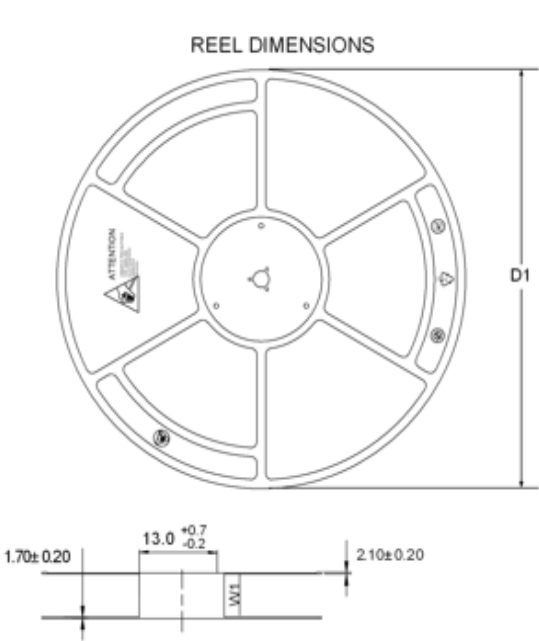
Unit in mm

Marking Information



Note:
G10N150KM = Product Name Code
KYWWZZZ = Date code
Contact ALKAIDSEMI sales for detail information

Tape & Reel Information



A0: Dimension designed to accommodate the component width
B0: Dimension designed to accommodate the component length
K0: Dimension designed to accommodate the component thickness
W: Overall width of the carrier tape
P0: Pitch between successive cavity centers and sprocket hole
P1: Pitch between successive cavity centers
P2: Pitch between sprocket hole
T: Tape material thickness
D1: Reel Diameter
W1: Reel Width

DIMENSIONS(Unit:mm)										
Reel	D1	W1								Material
	330	16.4								Hips
Tape	P0	P1	P2	W	A0	B0	K0	T	Pin 1 Quadrant	Material
	2	8	4	16	6.9	10.5	2.7	0.3	Q1	PC
All dimensions are nominal										

Revision History

Revision	Released	Remark
Rev.1.0	2024	Initial Release

Disclaimer

The information given in this document describes the independent performance of the product, but similar performance is not guaranteed under other working conditions, and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Alkaidsemi assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability. Customers using or selling these products for use in medical, life-saving, or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.